## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Examiner:

Khiem D. Nguyen

Toshikazu Okubo et al.

Serial No.

10/550,153

Art Unit:

2823

Filed:

September 20, 2005

Confirmation No.: 1053

Title:

Method for Analyzing Copper Electroplating Solution, Apparatus for the

Analysis, and Method for Fabricating Semiconductor Product

## RESPONSE TO OFFICE ACTION

Dear Examiner Nguyen:

This is a response to the Office Action dated July 3, 2008, which has a shortened statutory period for reply that ends on October 3, 2008. Please amend the above-identified application as follows.

Amendments to the Claims begins on page 2 of this paper.

Remarks begin on page 10 of this paper.